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48 1 1 OE

47 1 1A1

46 1A2

45 GND

44 T 1A3

43 🛮 1A4

41 **1** 1A5

40 1A6

39 [] GND

38 1 1A7

37 **∏** 1A8

36 2A1

35 1 2A2

34 [] GND

33 2A3

32 **□** 2A4

30 2A5

29**∏** 2A6

28 | GND

27 2A7

26**∏** 2A8 25 1 2OE

31 VCCA

42 VCCA

**DGG OR DGV PACKAGE** (TOP VIEW)

1DIR [

1B1 🛛 2

1B2 🛛 3

GND 4

1B3 **∏** 

1B4 □

1B5 🛮 8

1B6 🛮 9

GND [] 10

1B8 **1** 12

2B1 1 13

2B2 [] 14

GND [] 15

2B3 **1** 16

2B4 **1** 17

2B5 🛮 19

2B6 [] 20

2B7 1 22

2B8 **1** 23

2DIR 🛮 24

GND 1 21

V<sub>CCB</sub> 18

1B7 [ 11

 $V_{\rm CCB}$  L

- Control Inputs VIH/VIL Levels Are Referenced to V<sub>CCA</sub> Voltage V<sub>CC</sub> Isolation Feature – If Either V<sub>CC</sub> Input Is at GND, Both Ports Are in the **High-Impedance State**
- Overvoltage-Tolerant Inputs/Outputs Allow Mixed-Voltage-Mode Data Communications
- **Fully Configurable Dual-Rail Design Allows** Each Port to Operate Over the Full 1.2-V to 3.6-V Power-Supply Range
- Ioff Supports Partial-Power-Down Mode Operation
- I/Os Are 4.6-V Tolerant
- Bus Hold on Data Inputs Eliminates the **Need for External Pullup/Pulldown** Resistors
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- **ESD Protection Exceeds JESD 22** 
  - 8000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

## description/ordering information

This 16-bit noninverting bus transceiver uses two

separate configurable power-supply rails. The SN74AVCH16T245 is optimized to operate with

 $V_{CCA}/V_{CCB} \ \text{set at 1.4 V to 3.6 V. It is operational with } V_{CCA}/V_{CCB} \ \text{as low as 1.2 V. The A port is designed to track}$ V<sub>CCA</sub>. V<sub>CCA</sub> accepts any supply voltage from 1.2 V to 3.6 V. The B port is designed to track V<sub>CCB</sub>. V<sub>CCB</sub> accepts any supply voltage from 1.2 V to 3.6 V. This allows for universal low-voltage bidirectional translation between any of the 1.2-V, 1.5-V, 1.8-V, 2.5-V, and 3.3-V voltage nodes.

The SN74AVCH16T245 is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (OE) input can be used to disable the outputs so the buses are effectively isolated.

The SN74AVCH16T245 is designed so that the control pins (1DIR, 2DIR,  $1\overline{OE}$ , and  $2\overline{OE}$ ) are supplied by  $V_{CCA}$ .

#### **ORDERING INFORMATION**

TA	PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	TSSOP – DGG	Tape and reel	SN74AVCH16T245GR	AVCH16T245
-40°C to 85°C	TVSOP - DGV	Tape and reel	SN74AVCH16T245VR	WJ245
-40 C to 85 C	VFBGA – GQL	Tape and reel	SN74AVCH16T245KR	WJ245
	VFBGA – ZQL (Pb-free)	Tape and reel	74AVCH16T245ZQLR	VVJ240

<sup>†</sup>Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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### description/ordering information (continued)

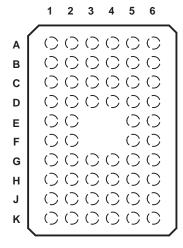
This device is fully specified for partial-power-down applications using I<sub>off</sub>. The I<sub>off</sub> circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The  $V_{CC}$  isolation feature ensures that if either  $V_{CC}$  input is at GND, then both ports are in the high-impedance state.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

To ensure the high-impedance state during power up or power down,  $\overline{\text{OE}}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

# GQL OR ZQL PACKAGE (TOP VIEW)



### terminal assignments

	1	2	3	4	5	6
Α	1DIR	NC	NC	NC	NC	1OE
В	1B2	1B1	GND	GND	1A1	1A2
С	1B4	1B3	VCCB	VCCA	1A3	1A4
D	1B6	1B5	GND	GND	1A5	1A6
Е	1B8	1B7			1A7	1A8
F	2B1	2B2			2A2	2A1
G	2B3	2B4	GND	GND	2A4	2A3
Н	2B5	2B6	VCCB	VCCA	2A6	2A5
J	2B7	2B8	GND	GND	2A8	2A7
K	2DIR	NC	NC	NC	NC	2OE

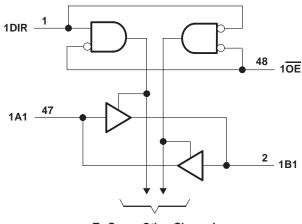
NC - No internal connection

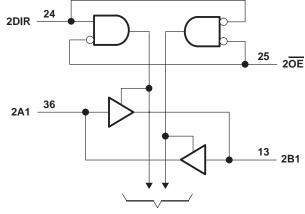
# FUNCTION TABLE (each 8-bit section)

INP	UTS							
ŌĒ	DIR	OPERATION						
L	L	B data to A bus						
L	Н	A data to B bus						
Н	X	Isolation						

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## logic diagram (positive logic)





**To Seven Other Channels** 

To Seven Other Channels

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CCA</sub> and V <sub>CCB</sub>
Input voltage range, V <sub>I</sub> (see Note 1): I/O ports (A port)
I/O ports (B port)
Control inputs
Voltage range applied to any output in the high-impedance or power-off state, VO
(see Note 1): A port
B port
Voltage range applied to any output in the high or low state, V <sub>O</sub>
(see Notes 1 and 2): A port
B port
Input clamp current, $I_{IK}$ ( $V_I < 0$ )
Output clamp current, $I_{OK}$ ( $V_O < 0$ )
Continuous output current, I <sub>O</sub> ±50 mA
Continuous current through each V <sub>CCA</sub> , V <sub>CCB</sub> , and GND ±100 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 3): DGG package
DGV package 58°C/W
GQL/ZQL package
Storage temperature range, T <sub>stg</sub> 65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input voltage and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. The output positive-voltage rating may be exceeded up to 4.6 V maximum if the output current rating is observed.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.

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#### recommended operating conditions (see Notes 4 through 8)

			VCCI	Vcco	MIN	MAX	UNIT
VCCA	Supply voltage				1.2	3.6	V
V <sub>CCB</sub>	Supply voltage				1.2	3.6	V
			1.2 V to 1.95 V		V <sub>CCI</sub> × 0.65		
٧ <sub>IH</sub>	High-level input voltage	Data inputs (see Note 7)	1.95 V to 2.7 V		1.6		V
	voltage	(300 14010 1)	2.7 V to 3.6 V		2		1
			1.2 V to 1.95 V			V <sub>CCI</sub> × 0.35	
٧ <sub>IL</sub>	Low-level input voltage	Data inputs (see Note 7)	1.95 V to 2.7 V			0.7	V
	voltago	(000 14010 7)	2.7 V to 3.6 V			0.8	1
		DIR	1.2 V to 1.95 V		$V_{CCA} \times 0.65$		
٧ <sub>IH</sub>	High-level input voltage	(referenced to V <sub>CCA</sub> )	1.95 V to 2.7 V		1.6		V
	voltage	(see Note 8)	2.7 V to 3.6 V		2		
		DIR	1.2 V to 1.95 V			V <sub>CCA</sub> × 0.35	
V <sub>IL</sub>	Low-level input voltage	(referenced to V <sub>CCA</sub> )	1.95 V to 2.7 V			0.7	V
	voltage	(see Note 8)	2.7 V to 3.6 V			0.8	1
VI	Input voltage				0	3.6	V
\/ -	Outrot valtage	Active state			0	Vcco	V
VO	Output voltage	3-state			0	3.6	V
				1.2 V		-3	
				1.4 V to 1.6 V		-6	
loH	High-level output curre	nt		1.65 V to 1.95 V		-8	mA
				2.3 V to 2.7 V		-9	]
				3 V to 3.6 V		-12	
				1.2 V		3	
				1.4 V to 1.6 V		6	]
lOL	Low-level output currer	ıt		1.65 V to 1.95 V		8	mA
				2.3 V to 2.7 V		9	
				3 V to 3.6 V		12	
Δt/Δν	Input transition rise or f	all rate				5	ns/V
TA	Operating free-air temp	erature			-40	85	°C

NOTES: 4.  $V_{CCI}$  is the  $V_{CC}$  associated with the data input port.

- 5. V<sub>CCO</sub> is the V<sub>CC</sub> associated with the output port.
- $6. \quad \text{All unused data inputs of the device must be held at $V_{\text{CCI}}$ or $GND$ to ensure proper device operation. Refer to the $TI$ application report,}\\$ Implications of Slow or Floating CMOS Inputs, literature number SCBA004.
- 7. For V<sub>CCI</sub> values not specified in the data sheet, V<sub>IH</sub> min = V<sub>CCI</sub> × 0.7 V, V<sub>IL</sub> max = V<sub>CCI</sub> × 0.3 V.

  8. For V<sub>CCI</sub> values not specified in the data sheet, V<sub>IH</sub> min = V<sub>CCA</sub> × 0.7 V, V<sub>IL</sub> max = V<sub>CCA</sub> × 0.3 V.

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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Notes 9 and 10)

				.,	.,	T,	4 = 25°C	;	-40°C TO 85°C		LINUT	
PARAMET	ER	TEST CONI	DITIONS	VCCA	VCCB	MIN	TYP	MAX	MIN	MAX	UNIT	
		$I_{OH} = -100  \mu A$		1.2 V to 3.6 V	1.2 V to 3.6 V				Vcco - 0	.2 V		
		$I_{OH} = -3 \text{ mA}$	]	1.2 V	1.2 V		0.95					
.,		I <sub>OH</sub> = -6 mA	],, ,,	1.4 V	1.4 V				1.05		.,	
VOH		$I_{OH} = -8 \text{ mA}$	VI = VIH	1.65 V	1.65 V				1.2		V	
		$I_{OH} = -9 \text{ mA}$	1	2.3 V	2.3 V				1.75			
		I <sub>OH</sub> = -12 mA	1	3 V	3 V		2.3					
		I <sub>OL</sub> = 100 μA		1.2 V to 3.6 V	1.2 V to 3.6 V					0.2		
		I <sub>OL</sub> = 3 mA	1	1.2 V	1.2 V		0.15					
		I <sub>OL</sub> = 6 mA	1	1.4 V	1.4 V					0.35		
VOL		I <sub>OL</sub> = 8 mA	$V_I = V_{IL}$	1.65 V	1.65 V					0.45	V	
		I <sub>OL</sub> = 9 mA	1	2.3 V	2.3 V					0.55		
		I <sub>OL</sub> = 12 mA	1	3 V	3 V					0.7		
1.	ontrol puts	$V_I = V_{CCA}$ or G	ND	1.2 V to 3.6 V	1.2 V to 3.6 V		±0.025	±0.25		±1	μΑ	
		V <sub>I</sub> = 0.42 V		1.2 V	1.2 V		25					
		V <sub>I</sub> = 0.49 V		1.4 V	1.4 V				15			
I <sub>BHL</sub> †		V <sub>I</sub> = 0.58 V		1.65 V	1.65 V				25		μΑ	
		V <sub>I</sub> = 0.7 V		2.3 V	2.3 V				45			
		V <sub>I</sub> = 0.8 V		3.3 V	3.3 V				100			
		V <sub>I</sub> = 0.78 V		1.2 V	1.2 V		-25					
		V <sub>I</sub> = 0.91 V		1.4 V	1.4 V				-15			
I <sub>BHH</sub> ‡		V <sub>I</sub> = 1.07 V		1.65 V	1.65 V				-25		μΑ	
		V <sub>I</sub> = 1.6 V		2.3 V	2.3 V				-45			
		V <sub>I</sub> = 2 V		3.3 V	3.3 V				-100			
				1.2 V	1.2 V		50					
				1.6 V	1.6 V				125			
I <sub>BHLO</sub> §		$V_I = 0$ to $V_{CC}$		1.95 V	1.95 V				200		μΑ	
				2.7 V	2.7 V				300			
				3.6 V	3.6 V				500			
				1.2 V	1.2 V		-50					
	внно <sup>¶</sup>			1.6 V	1.6 V				-125			
I <sub>BHHO</sub> ¶		$V_I = 0$ to $V_{CC}$		1.95 V	1.95 V				-200		μΑ	
_,			2.7 V	2.7 V				-300		·		
			3.6 V	3.6 V				-500				

<sup>†</sup> The bus-hold circuit can sink at least the minimum low sustaining current at V<sub>IL</sub> max. I<sub>BHL</sub> should be measured after lowering V<sub>IN</sub> to GND and then raising it to V<sub>IL</sub> max.



<sup>&</sup>lt;sup>‡</sup> The bus-hold circuit can source at least the minimum high sustaining current at V<sub>IH</sub> min. I<sub>BHH</sub> should be measured after raising V<sub>IN</sub> to V<sub>CC</sub> and then lowering it to V<sub>IH</sub> min.

<sup>§</sup> An external driver must source at least I<sub>BHLO</sub> to switch this node from low to high.

<sup>¶</sup> An external driver must sink at least IBHHO to switch this node from high to low.

NOTES: 9. V<sub>CCO</sub> is the V<sub>CC</sub> associated with the output port.

<sup>10.</sup> V<sub>CCI</sub> is the V<sub>CC</sub> associated with the input port.

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### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Notes 9 and 10) (continued)

PARA	METER	TEST CONDI	TIONS	VCCA	V <sub>CCB</sub>	T,	դ = 25°C	;	–40°0 85°	UNIT	
						MIN	TYP	MAX	MIN	MAX	
	A port	V an V 040 2 C	.,	0 V	0 to 3.6 V		±0.1	±2.5		±5	^
l <sub>off</sub>	B port	$V_I$ or $V_O = 0$ to 3.6 V		0 to 3.6 V	0 V		±0.1	±2.5		±5	μА
,,	A or B ports	$V_O = V_{CCO}$ or $\overline{OE} = V_{IH}$		3.6 V	3.6 V		±0.5	±2.5		±5	
loz#	B port	GND, V <sub>I</sub> = V <sub>CCI</sub> or GND	$\overline{OE} = don't$	0 V	3.6 V					±5	μА
	A port	1 1 - 100 0 0 0 0	care 3.6 V 0 V								
				1.2 V to 3.6 V	1.2 V to 3.6 V					25	
ICCA		$V_I = V_{CCI}$ or GND,	$I_O = 0$	0 V	3.6 V					-5	μА
				3.6 V	0 V					25	
				1.2 V to 3.6 V	1.2 V to 3.6 V					25	
ICCB		$V_I = V_{CCI}$ or GND,	$I_O = 0$	0 V	3.6 V					25	μΑ
				3.6 V	0 V					-5	
ICCA -	⊦ ICCB	$V_I = V_{CCI}$ or GND,	IO = 0	1.2 V to 3.6 V	1.2 V to 3.6 V					45	μΑ
Ci	Control inputs	V <sub>I</sub> = 3.3 V or GND		3.3 V	3.3 V		3.5				pF
C <sub>io</sub>	A or B ports	V <sub>O</sub> = 3.3 V or GND		3.3 V	3.3 V		7				pF

<sup>#</sup> For I/O ports, the parameter IOZ includes the input leakage current.

NOTES: 9. VCCO is the VCC associated with the output port.

10. V<sub>CCI</sub> is the V<sub>CC</sub> associated with the input port.

## switching characteristics over recommended operating free-air temperature range, $V_{CCA} = 1.2 V$ (see Figure 1)

DADAMETED	FROM	то	V <sub>CCB</sub> = 1.2 V	V <sub>CCB</sub> = 1.5 V	V <sub>CCB</sub> = 1.8 V	V <sub>CCB</sub> = 2.5 V	V <sub>CCB</sub> = 3.3 V	LINUT
PARAMETER	(INPUT)	(OUTPUT)	TYP	TYP	TYP	TYP	TYP	UNIT
<sup>t</sup> PLH			4.1	3.3	3	2.8	3.2	
t <sub>PHL</sub>	Α	В	4.1	3.3	3	2.8	3.2	ns
t <sub>PLH</sub>			4.4	4	3.8	3.6	3.5	
t <sub>PHL</sub>	В	Α	4.4	4	3.8	3.6	3.5	ns
<sup>t</sup> PZH	ŌĒ		6.4	6.4	6.4	6.4	6.4	
tPZL	OE	Α	6.4	6.4	6.4	6.4	6.4	ns
t <sub>PZH</sub>	ŌĒ		6	4.6	4	3.4	3.2	
t <sub>PZL</sub>	OE	В	6	4.6	4	3.4	3.2	ns
t <sub>PHZ</sub>	ŌĒ		6.6	6.6	6.6	6.6	6.8	
tPLZ	OE	Α	6.6	6.6	6.6	6.6	6.8	ns
t <sub>PHZ</sub>	ŌĒ		6	4.9	4.9	4.2	5.3	
<sup>t</sup> PLZ	OE	В	6	4.9	4.9	4.2	5.3	ns

## **SN74AVCH16T245 16-BIT DUAL-SUPPLY BUS TRANSCEIVER** WITH CONFIGURABLE VOLTAGE TRANSLATION AND 3-STATE OUTPUTS SCES587B - AUGUST 2004 - REVISED APRIL 2005

## switching characteristics over recommended operating free-air temperature range, $V_{CCA} = 1.5 V \pm 0.1 V$ (see Figure 1)

PARAMETER	FROM (INPUT)	TO	V <sub>CCB</sub> = 1.2 V	V <sub>CCB</sub> =		V <sub>CCB</sub> = ± 0.1		V <sub>CCB</sub> =		V <sub>CCB</sub> =		UNIT										
	(INPUI)	(OUTPUT)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX											
t <sub>PLH</sub>	А	В	3.6	0.5	6.2	0.5	5.2	0.5	4.1	0.5	3.7											
t <sub>PHL</sub>	А	Б	3.6	0.5	6.2	0.5	5.2	0.5	4.1	0.5	3.7	ns										
t <sub>PLH</sub>	В	Α	3.3	0.5	6.2	0.5	5.9	0.5	5.6	0.5	5.5	20										
t <sub>PHL</sub>	В	А	3.3	0.5	6.2	0.5	5.9	0.5	5.6	0.5	5.5	ns										
<sup>t</sup> PZH	ŌĒ		4.3	1	10.1	1	10.1	1	10.1	1	10.1											
t <sub>PZL</sub>	OE	А	4.3	1	10.1	1	10.1	1	10.1	1	10.1	ns										
<sup>t</sup> PZH	ŌĒ	В	5.6	1	10.1	0.5	8.1	0.5	5.9	0.5	5.2											
tPZL	OE	В	5.6	1	10.1	0.5	8.1	0.5	5.9	0.5	5.2	ns										
t <sub>PHZ</sub>	ŌĒ	Δ.	4.5	1.5	9.1	1.5	9.1	1.5	9.1	1.5	9.1											
t <sub>PLZ</sub>	OE	Α	4.5	1.5	9.1	1.5	9.1	1.5	9.1	1.5	9.1	ns										
t <sub>PHZ</sub>	<del></del>		5.5	1.5	8.7	1.5	7.5	1	6.5	1	6.3											
t <sub>PLZ</sub>	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	В	5.5	1.5	8.7	1.5	7.5	1	6.5	1	6.3	ns

## switching characteristics over recommended operating free-air temperature range, $V_{CCA} = 1.8 V \pm 0.15 V$ (see Figure 1)

PARAMETER	FROM	TO	V <sub>CCB</sub> = 1.2 V	V <sub>CCB</sub> =		V <sub>CCB</sub> = ± 0.1		V <sub>CCB</sub> =		V <sub>CCB</sub> =		UNIT																					
	(INPUT)	(OUTPUT)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX																						
t <sub>PLH</sub>	٨	В	3.4	0.5	5.9	0.5	4.8	0.5	3.7	0.5	3.3	20																					
tPHL	Α	В	3.4	0.5	5.9	0.5	4.8	0.5	3.7	0.5	3.3	ns																					
tPLH	В	^	3	0.5	5.2	0.5	4.8	0.5	4.5	0.5	4.4																						
t <sub>PHL</sub>	В	Α	3	0.5	5.2	0.5	4.8	0.5	4.5	0.5	4.4	ns																					
<sup>t</sup> PZH	ŌĒ	^	3.4	1	7.8	1	7.8	1	7.8	1	7.8																						
tPZL	OE	OE .	Α	3.4	1	7.8	1	7.8	1	7.8	1	7.8	ns																				
<sup>t</sup> PZH	ŌĒ	В	5.4	1	9.2	0.5	7.4	0.5	5.3	0.5	4.5	20																					
tPZL	OE	В	5.4	1	9.2	0.5	7.4	0.5	5.3	0.5	4.5	ns																					
t <sub>PHZ</sub>	<u></u>	^	4.2	1.5	7.7	1.5	7.7	1.5	7.7	1.5	7.7																						
tPLZ	OE	ŌĒ	ŌĒ	OĒ	OE A	4.2	1.5	7.7	1.5	7.7	1.5	7.7	1.5	7.7	ns																		
t <sub>PHZ</sub>	ŌĒ	В	5.2	1.5	8.4	1.5	7.1	1	5.9	1	5.7																						
t <sub>PLZ</sub>		ŌĒ	ŌĒ	ŌĒ	ŌĒ	OE	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	OĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	В	5.2	1.5	8.4	1.5	7.1	1	5.9	1	5.7

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# switching characteristics over recommended operating free-air temperature range, $V_{CCA}$ = 2.5 V $\pm$ 0.2 V (see Figure 1)

PARAMETER	FROM (INPUT)	TO	V <sub>CCB</sub> = 1.2 V	V <sub>CCB</sub> =		V <sub>CCB</sub> = ± 0.1		V <sub>CCB</sub> =		V <sub>CCB</sub> =		UNIT										
	(INPUT)	(OUTPUT)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX											
t <sub>PLH</sub>	٨	В	3.2	0.5	5.6	0.5	4.5	0.5	3.3	0.5	2.8											
t <sub>PHL</sub>	Α	В	3.2	0.5	5.6	0.5	4.5	0.5	3.3	0.5	2.8	ns										
t <sub>PLH</sub>	В		2.6	0.5	4.1	0.5	3.7	0.5	3.3	0.5	3.2											
t <sub>PHL</sub>	В	Α	2.6	0.5	4.1	0.5	3.7	0.5	3.3	0.5	3.2	ns										
<sup>t</sup> PZH	ŌĒ		2.5	0.5	5.3	0.5	5.3	0.5	5.3	0.5	5.3											
tPZL	OE	A	2.5	0.5	5.3	0.5	5.3	0.5	5.3	0.5	5.3	ns										
<sup>t</sup> PZH	ŌE		5.2	0.5	9.4	0.5	7.3	0.5	5.1	0.5	4.5											
tPZL	OE	В	5.2	0.5	9.4	0.5	7.3	0.5	5.1	0.5	4.5	ns										
t <sub>PHZ</sub>	<u></u>	Δ.	3	1	6.1	1	6.1	1	6.1	1	6.1											
tPLZ	ŌĒ	А	3	1	6.1	1	6.1	1	6.1	1	6.1	ns										
t <sub>PHZ</sub>	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ		5	1	7.9	1	6.6	1	6.1	1	5.2						
t <sub>PLZ</sub>							OE	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	В	5	1	7.9	1

# switching characteristics over recommended operating free-air temperature range, $V_{CCA}$ = 3.3 V $\pm$ 0.3 V (see Figure 1)

PARAMETER	FROM	TO	V <sub>CCB</sub> = 1.2 V	V <sub>CCB</sub> =		V <sub>CCB</sub> = ± 0.1		V <sub>CCB</sub> = ± 0.2		V <sub>CCB</sub> = ± 0.3		UNIT																			
	(INPUT)	(OUTPUT)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX																				
t <sub>PLH</sub>	٨		3.2	0.5	5.5	0.5	4.4	0.5	3.2	0.5	2.7																				
tPHL	Α	В	3.2	0.5	5.5	0.5	4.4	0.5	3.2	0.5	2.7	ns																			
t <sub>PLH</sub>	В		2.8	0.5	3.7	0.5	3.3	0.5	2.8	0.5	2.7																				
t <sub>PHL</sub>	В	А	2.8	0.5	3.7	0.5	3.3	0.5	2.8	0.5	2.7	ns																			
t <sub>PZH</sub>	ŌĒ		2.2	0.5	4.3	0.5	4.2	0.5	4.1	0.5	4																				
tPZL	OE	А	2.2	0.5	4.3	0.5	4.2	0.5	4.1	0.5	4	ns																			
t <sub>PZH</sub>	ŌĒ	В	5.1	0.5	9.3	0.5	7.2	0.5	4.9	0.5	4																				
tPZL	OE	В	5.1	0.5	9.3	0.5	7.2	0.5	4.9	0.5	4	ns																			
t <sub>PHZ</sub>	<u></u>		3.4	0.5	5	0.5	5	0.5	5	0.5	5																				
t <sub>PLZ</sub>	ŌĒ	А	3.4	0.5	5	0.5	5	0.5	5	0.5	5	ns																			
t <sub>PHZ</sub>	<u> </u>		4.9	1	7.7	1	6.5	1	5.2	0.5	5																				
tPLZ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	OË	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	В	4.9	1	7.7	1	6.5	1	5.2	0.5	5	ns

# **SN74AVCH16T245** 16-BIT DUAL-SUPPLY BUS TRANSCEIVER WITH CONFIGURABLE VOLTAGE TRANSLATION AND 3-STATE OUTPUTS SCESS87B - AUGUST 2004 - REVISED APRIL 2005

## operating characteristics, $T_A = 25^{\circ}C$

PARAMETER			TEST CONDITIONS	V <sub>CCA</sub> = V <sub>CCB</sub> = 1.2 V	V <sub>CCA</sub> = V <sub>CCB</sub> = 1.5 V	V <sub>CCA</sub> = V <sub>CCB</sub> = 1.8 V	V <sub>CCA</sub> = V <sub>CCB</sub> = 2.5 V	V <sub>CCB</sub> = 3.3 V	UNIT	
		CONDITIONS	TYP	TYP	TYP	TYP	TYP			
	A to B	Outputs enabled		1	1	1	1	2		
c <sub>pdA</sub> †	Alob	Outputs disabled	$C_L = 0$ , f = 10  MHz, $t_r = t_f = 1 \text{ ns}$	1	1	1	1	1	-F	
OpdA	B to A	Outputs enabled			13	13	14	15	16	pF
		Outputs disabled		1	1	1	1	1		
	A to B	Outputs enabled	$C_L = 0$ , f = 10  MHz, $t_{\Gamma} = t_f = 1 \text{ ns}$	13	13	14	15	16		
C <sub>pdB</sub> †	A to B	Outputs disabled		1	1	1	1	1	pF	
~paB₁	B to A	Outputs enabled			1	1	1	1	2	рг
		Outputs disabled		1	1	1	1	1		

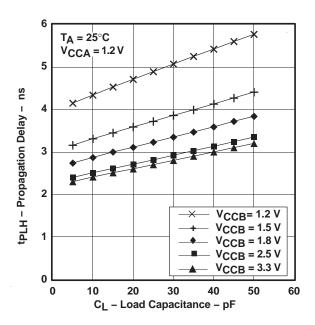
<sup>†</sup> Power-dissipation capacitance per transceiver

## typical total static power consumption ( $I_{CCA} + I_{CCB}$ )

Table 1

V <sub>CCB</sub>	V <sub>CCA</sub>											
	0 V	1.2 V	1.5 V	1.8 V	2.5 V	3.3 V	UNIT					
0 V	0	< 0.5	< 0.5	< 0.5	< 0.5	< 0.5						
1.2 V	< 0.5	< 1	< 1	< 1	< 1	1						
1.5 V	< 0.5	< 1	< 1	< 1	< 1	1						
1.8 V	< 0.5	< 1	< 1	< 1	< 1	< 1	μΑ					
2.5 V	< 0.5	1	< 1	< 1	< 1	< 1						
3.3 V	< 0.5	1	< 1	< 1	< 1	< 1						

#### TYPICAL CHARACTERISTICS



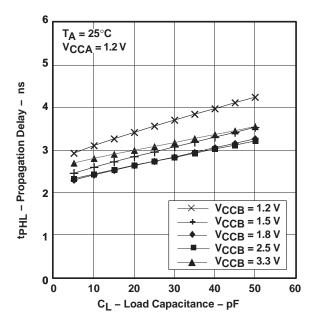
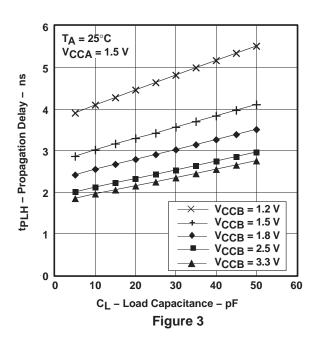
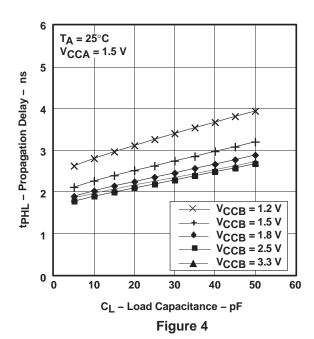


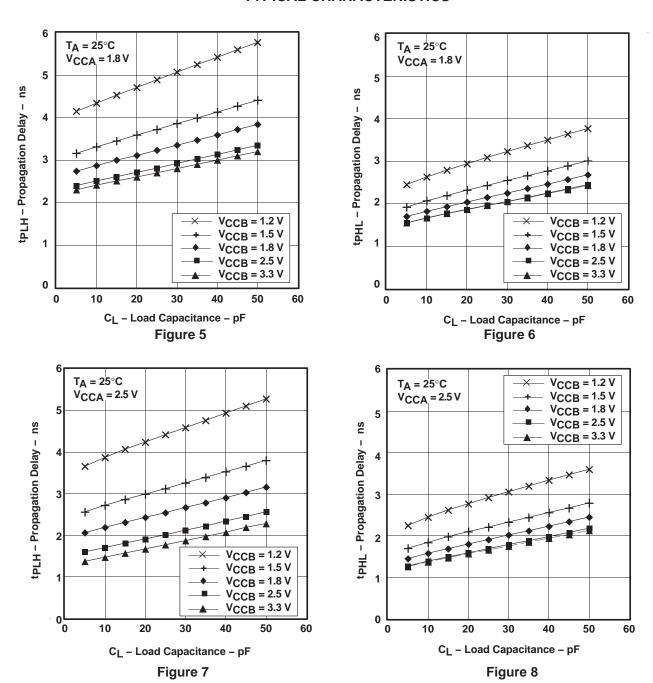
Figure 1



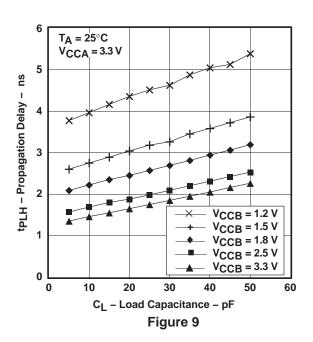


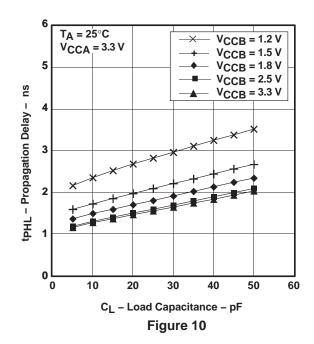


#### **TYPICAL CHARACTERISTICS**



## **TYPICAL CHARACTERISTICS**



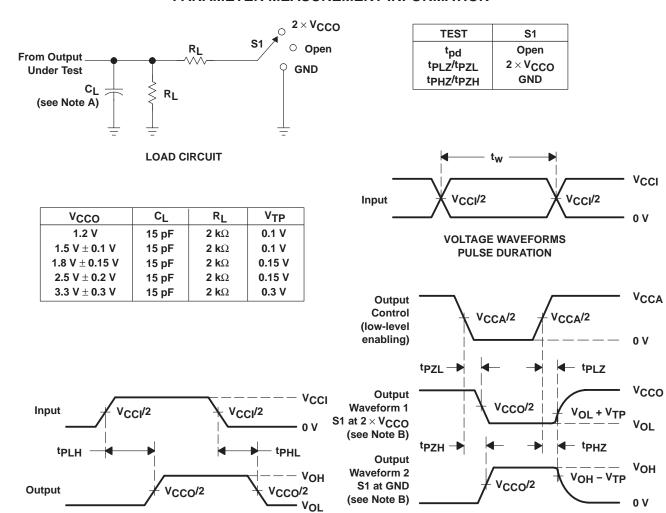


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**VOLTAGE WAVEFORMS** 

**ENABLE AND DISABLE TIMES** 

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $dv/dt \geq$  1 V/ns,  $dv/dt \geq$  1 V/ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G. tpLH and tpHL are the same as tpd.
- H. VCCI is the VCC associated with the input port.
- I. VCCO is the VCC associated with the output port.

**VOLTAGE WAVEFORMS** 

**PROPAGATION DELAY TIMES** 

Figure 11. Load Circuit and Voltage Waveforms







20-May-2013

#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)		(3)		(4/5)	
74AVCH16T245GRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AVCH16T245	Samples
74AVCH16T245GRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AVCH16T245	Samples
74AVCH16T245VRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	WJ245	Samples
74AVCH16T245VRG4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	WJ245	Samples
74AVCH16T245ZQLR	ACTIVE	BGA MICROSTAR JUNIOR	ZQL	56	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	WJ245	Samples
SN74AVCH16T245GQLR	OBSOLETE	BGA MICROSTAR JUNIOR	GQL	56		TBD	Call TI	Call TI	-40 to 85	WJ245	
SN74AVCH16T245GR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AVCH16T245	Samples
SN74AVCH16T245VR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	WJ245	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



### PACKAGE OPTION ADDENDUM

20-May-2013

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<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

## PACKAGE MATERIALS INFORMATION

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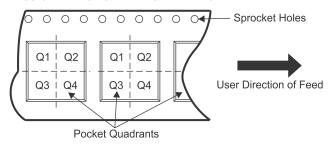
## TAPE AND REEL INFORMATION





Α0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74AVCH16T245ZQLR	BGA MI CROSTA R JUNI OR	ZQL	56	1000	330.0	16.4	4.8	7.3	1.5	8.0	16.0	Q1
SN74AVCH16T245GR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74AVCH16T245VR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1

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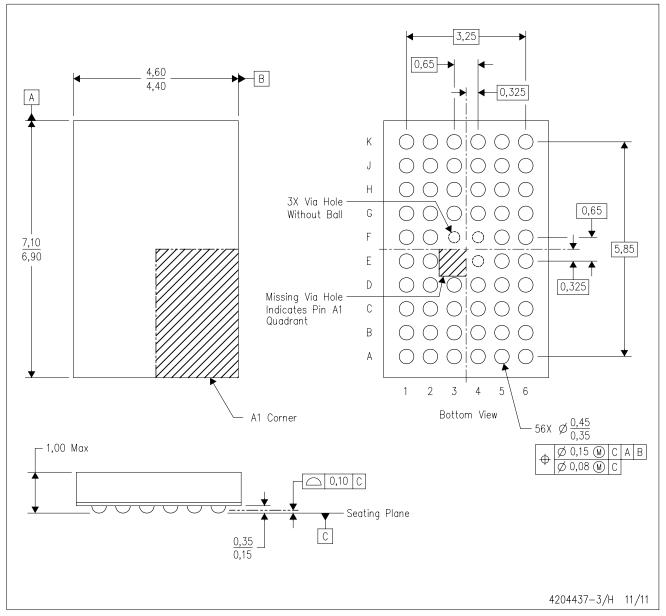


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74AVCH16T245ZQLR	BGA MICROSTAR JUNIOR	ZQL	56	1000	336.6	336.6	28.6
SN74AVCH16T245GR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74AVCH16T245VR	TVSOP	DGV	48	2000	367.0	367.0	38.0

## ZQL (R-PBGA-N56)

## PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-285 variation BA-2.
- D. This package is Pb-free. Refer to the 56 GQL package (drawing 4200583) for tin-lead (SnPb).

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## DGV (R-PDSO-G\*\*)

#### 24 PINS SHOWN

#### **PLASTIC SMALL-OUTLINE**



NOTES: A. All linear dimensions are in millimeters.

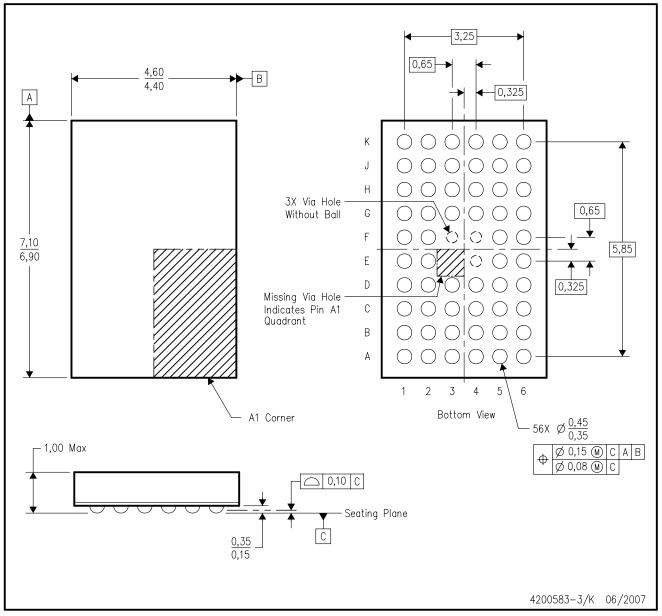
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194

## GQL (R-PBGA-N56)

## PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-285 variation BA-2.
- D. This package is tin-lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead-free.



## DGG (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

#### **48 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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